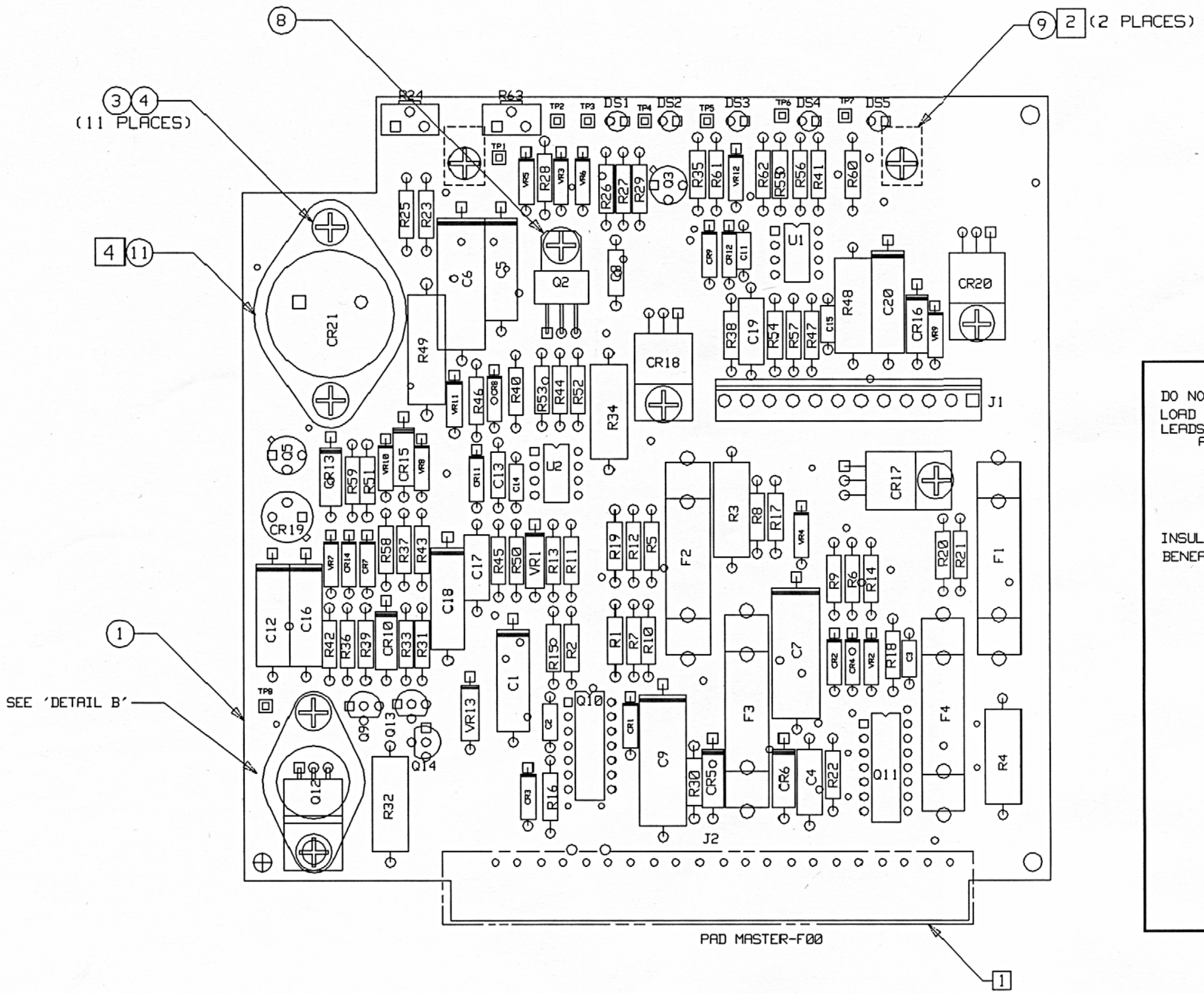
ENGINEERING RESPONSIBILITY 10 SEPIA

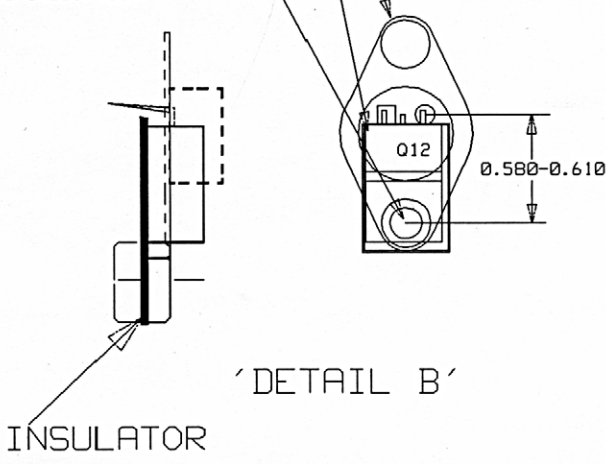
D-08901-60311-1

SYM	REVISIONS	APPROVED	DATE
A	AS ISSUED PER PCO 10-6128	D.WHITCOMB/RF	10/18/90
B	CHG Q12 ADD DETAIL B PER PCO 10-7032	B.GAINES/CAP	04/21/92

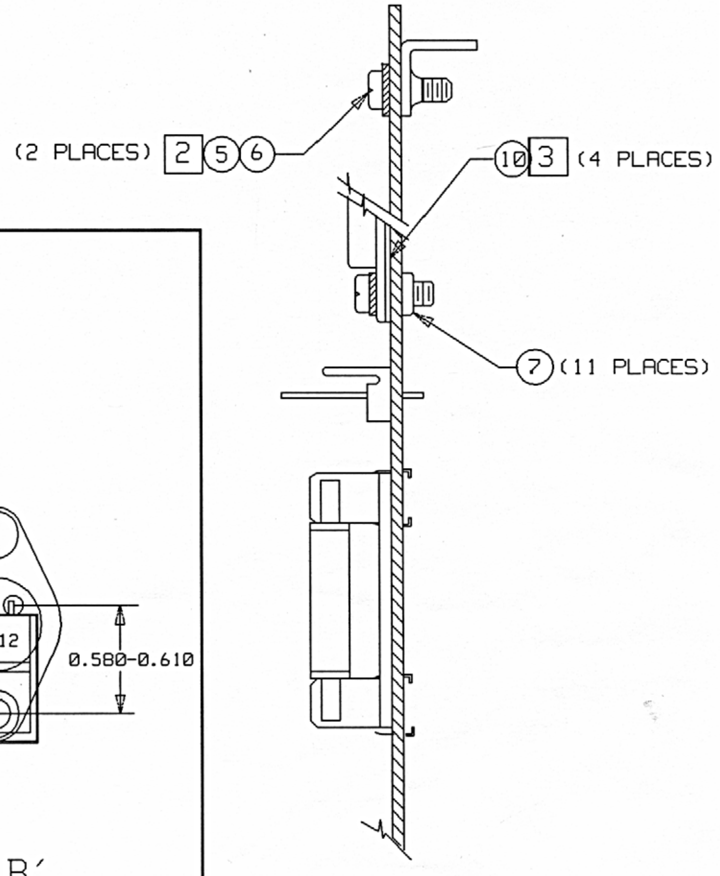


DO NOT LOAD OLD Q12 (METAL PACKAGE).
LOAD NEW T0220 PACKAGE IN IT'S PLACE.
LEADS ON NEW Q12 MUST BE PREFORMED AS SPECIFIED BELOW.
- a. CENTER TO LEAD .050 MAX.
- b. EXTERIOR LEADS TO BE .200 MAX.
- c. EXTERIOR LEADS TO BE BENT 0.580-0.610 FROM CENTER OF MOUNTING HOLE.

INSULATOR 0340-1209 TO BE PLACED BENEATH Q12 AS INDICATED.



'DETAIL B'



'DETAIL A'

NOTES: UNLESS OTHERWISE SPECIFIED

1. APPLY FLEXIBLE SOLDER MASK BEFORE FLOW SOLDER TO AREAS SHOWN DASHED AND OVER MOUNTING HARDWARE FOR CR17, CR18, CR20, CR21, Q12, & MOUNTING HOLES FOR ITEM 9.
2. INSTALL ITEMS 5,6&9 AFTER FLOW SOLDER
3. INSTALL ITEM 10 AT LOCATION SHOWN FOR Q4,Q6,Q7&Q12 BEFORE FLOW SOLDER.
4. INSTALL ITEM 11 (INSULATOR) BETWEEN Q1 AND PC BD BEFORE FLOW SOLDER.
5. INSTALL SUGAR BEADS ON COMPONENT LEADS OF R3,R4,R32,E34&R48 BEFORE FLOW SOLDER TO ELEVATE COMPONENTS OFF OF BD.
6. NO INSULATOR UNDER Q8. BEND LEADS TO KEEP PART OFF SURFACE OF PCB.

~~DO NOT SCALE THIS DRAWING~~
~~UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES.~~
~~TOLERANCES~~
~~.XX = ±~~
~~.XXX = ±~~
~~ANGLE = ±~~
~~• ADHERENCE TO DWG A-5951-1561-1 (CO. STD. SECTION 608) REQUIRED~~

R. FALLER DRAWN BY	9-14-90 DATE	PWA PWR SUPPLY REG'S TITLE	HEWLETT PACKARD
D.WHITCOMB ENGINEER/CHECKER	9-14-90		08901-60311 PART NUMBER
DAVE WHITCOMB RELEASE TO PROD.	18OCT90		
SUPERSEDES DWG.		NONE SCALE	SHEET 1 OF 1

D-08901-60311-1